

### **AMENDMENTS TO THE CLAIMS:**

1. (Original) A semiconductor wafer comprising:
  - a first principal side and a second principal side opposite to each other;
  - a first bevel contour and a second bevel contour provided at an outer periphery of the first principal side and the second principal side;
  - a first recess formed in the first bevel contour; and
  - a first type of ID mark configured by a protruding dot provided on a bottom face of the first recess.
2. (Original) The semiconductor wafer of claim 1, wherein an inclination angle of the bottom face of the first recess to the first principal side is in a range of 30° to 60°.
3. (Original) The semiconductor wafer of claim 1, wherein the first type of ID marks are formed displaced from each other in the thickness direction and the circumferential direction of the semiconductor wafer, at least at the bottom face of the first recess.
4. (Original) The semiconductor wafer of claim 1, wherein the first type of ID mark is provided at a flat part formed in the bottom face of the first recess.
5. (Original) The semiconductor wafer of claim 4, wherein the flat part comprises a minute dot group.

6. (Original) The semiconductor wafer of claim 5, wherein height of the minute dot group is equal to or less than 50nm, and height of a first dot is more than 100nm.

7. (Original) The semiconductor wafer of claim 1, further comprising a second recess formed at the second bevel contour and provided with the first type of ID mark at a bottom of the second recess part.

8. (Original) The semiconductor wafer of claim 1, wherein the first type of ID mark is provided at the first recess adjacent to a standard position at an outer peripheral part of the first bevel contour, and at a third recess on the first bevel contour of an opposite side of the first recess adjacent to the standard position.

9. (Original) The semiconductor wafer of claim 8, wherein the standard position is a standard sign showing a crystalline direction of the wafer.

10. (Original) The semiconductor wafer of claim 8, wherein the standard position is one of a flat orientation, notch and a seal.

11. - 12. (Cancelled)

13. (Currently amended) ~~[[The]] A semiconductor wafer of claim 11, wherein comprising:~~  
a first principal side and a second principal side opposite to each other;

a first bevel contour and a second bevel contour provided at an outer peripheral part of the first principal side and the second principal side;

a [[the]] first type of ID mark of protruding dots [[is]] provided at a first recess adjacent to a notch at the outer peripheral part of the first bevel contour~~[[,]]~~; and

a [[the]] second type of ID mark of recessed dots [[is]] provided at a part of the first bevel contour adjacent to the notch on the opposite side of the first type of ID mark with the notch interposed therebetween.

14. (Original) The semiconductor wafer of claim 13, wherein a standard position is a standard sign showing a crystalline direction of the wafer.

15. (Original) The semiconductor wafer of claim 13, wherein the standard position is one of an orientation, notch and a minute seal.

16. - 36. (Cancelled)